

- Preface p. xv
- Chapter 1. The Semiconductor Industry p. 1
 - Birth of an Industry p. 1
 - The Solid State Era p. 3
 - Integrated Circuits (I.C.'s) p. 4
 - Process and Product Trends p. 5
 - Industry Organization p. 11
 - Stages of Manufacturing p. 13
 - The Development Decade (1951-1960) p. 16
 - The Processing Decade (1961-1970) p. 18
 - The Production Decade (1971-1980) p. 19
 - The Automation Decade (1981-1990) p. 20
 - The Production Era (1991-2000) p. 20
 - The Nano Era p. 22
 - Key Terms p. 23
 - Review Questions p. 23
 - References p. 23
- Chapter 2. Semiconductor Materials and Process Chemicals p. 25
 - Atomic Structure p. 26
 - The Periodic Table of the Elements p. 27
 - Electrical Conduction p. 29
 - Dielectrics and Capacitors p. 30
 - Intrinsic Semiconductors p. 31
 - Doped Semiconductors p. 31
 - Electron and Hole Conduction p. 34
 - Carrier Mobility p. 36
 - Semiconductor Production Materials p. 37
 - Semiconducting Compounds p. 37
 - Silicon Germanium p. 38
 - Ferroelectric Materials p. 38
 - Process Chemicals p. 39
 - States of Matter p. 41
 - Plasma State p. 42
 - Properties of Matter p. 42
 - Pressure and Vacuum p. 43
 - Acids, Alkalis, and Solvents p. 45
 - The Safety Material Data Sheet p. 47
 - Key Terms and Concepts p. 47
 - Review Questions p. 47
 - References p. 48
- Chapter 3. Manufacturing Wafers p. 49
 - Introduction p. 50
 - Semiconductor Silicon Preparation p. 50
 - Crystalline Materials p. 51
 - Crystal Orientation p. 52
 - Crystal Growth p. 53

- Crystal and Wafer Quality p. 57
- Wafer Preparation p. 59
- Wafer Slicing p. 61
- Wafer Marking p. 62
- Rough Polish p. 62
- Chemical Mechanical Polishing (CMP) p. 63
- Backside Processing p. 64
- Double-Sided Polishing p. 64
- Edge Grinding and Polishing p. 64
- Wafer Evaluation p. 65
- Oxidation p. 65
- Packaging p. 65
- Epi on Silicon Wafers p. 66
- Key Terms p. 66
- Review Questions p. 66
- References p. 67
- Chapter 4. Overview of Wafer Fabrication p. 69
- Goal of Wafer Fabrication p. 70
- Wafer Terminology p. 70
- Basic Wafer-Fabrication Operations p. 71
- Manufacturing Semiconductor Devices and Circuits p. 75
- Example Fabrication Process p. 79
- Chip Terminology p. 82
- Wafer Sort p. 82
- Packaging p. 85
- Summary p. 85
- Key Concepts and Terms p. 86
- Review Questions p. 86
- References p. 86
- Chapter 5. Contamination Control p. 87
- Introduction p. 88
- The Problem p. 88
- Contamination Sources p. 92
- Clean-Room Construction p. 101
- Clean-Room Materials and Supplies p. 114
- Clean-Room Maintenance p. 114
- Wafer Surface Cleaning p. 115
- Key Concepts and Terms p. 130
- Review Questions p. 130
- References p. 131
- Chapter 6. Process Yields p. 133
- Yield Measurement Points p. 133
- Accumulative Wafer-Fabrication Yield p. 134
- Wafer-Fabrication Yield Limiters p. 136
- Wafer-Sort Yield Factors p. 141
- Assembly and Final Test Yields p. 149

- Overall Process Yields p. 149
- Key Concepts and Terms p. 151
- Review Questions p. 151
- References p. 152
- Chapter 7. Oxidation p. 153
 - Silicon Dioxide Layer Uses p. 154
 - Thermal Oxidation Mechanisms p. 157
 - Thermal Oxidation Methods p. 163
 - Horizontal Tube Furnaces p. 164
 - Vertical Tube Furnaces p. 177
 - Fast Ramp Furnaces p. 179
 - Rapid Thermal Processing (RTP) p. 179
 - High-Pressure Oxidation p. 183
 - Oxidation Processes p. 185
 - Postoxidation Evaluation p. 186
 - Anodic Oxidation p. 188
 - Thermal Nitridation p. 188
 - Key Concepts and Terms p. 189
 - Review Questions p. 189
 - References p. 190
- Chapter 8. Basic Patterning--Surface Preparation to Exposure p. 193
 - Introduction p. 194
 - Overview of the Photomasking Process p. 195
 - Ten-Step Process p. 197
 - Basic Photoresist Chemistry p. 198
 - Photoresist Performance Factors p. 203
 - Comparison of Positive and Negative Resists p. 207
 - Physical Properties of Photoresists p. 209
 - Photomasking Processes p. 213
 - Surface Preparation p. 213
 - Photoresist Spinning p. 217
 - Soft Bake p. 222
 - Alignment and Exposure p. 227
 - Aligner System Comparison p. 239
 - Key Concepts and Terms p. 240
 - Review Questions p. 240
 - References p. 240
- Chapter 9. Basic Patterning--Developing to Final Inspection p. 243
 - Development p. 243
 - Hard Bake p. 250
 - Develop Inspect p. 252
 - Etch p. 256
 - Wet Etching p. 256
 - Dry Etch p. 263
 - Resist Stripping p. 270
 - Final Inspection p. 274

- Mask Making p. 274
- Summary p. 277
- Key Concepts and Terms p. 278
- Review Questions p. 278
- References p. 279
- Chapter 10. Advanced Photolithography Processes p. 281
- Optical Resolution Control p. 283
- Other Exposure Issues p. 288
- Pellicles p. 292
- Surface Problems p. 294
- Antireflective Coatings p. 295
- Planarization p. 297
- Photoresist Process Advances p. 298
- CMP Summary p. 308
- Improving Etch Definition p. 313
- Self-Aligned Structures p. 314
- Etch Profile Control p. 314
- The End of Optical Lithography? p. 315
- Key Concepts and Terms p. 316
- Review Questions p. 316
- References p. 316
- Chapter 11. Doping p. 319
- Definition of a Junction p. 319
- Formation of a Doped Region p. 320
- Formation of a Doped Region and Junction by Diffusion p. 321
- Diffusion Process Steps p. 326
- Deposition p. 326
- Drive-in-Oxidation p. 335
- Introduction to Ion Implantation p. 337
- Concept of Ion Implantation p. 340
- Ion Implantation System p. 340
- Dopant Concentration in Implanted Regions p. 348
- Evaluation of Implanted Layers p. 352
- Uses of Ion Implantation p. 354
- The Future of Doping p. 355
- Key Concepts and Terms p. 356
- Review Questions p. 356
- References p. 356
- Chapter 12. Deposition p. 359
- Introduction p. 359
- Chemical Vapor Deposition Basics p. 363
- CVD Process Steps p. 366
- CVD System Types p. 366
- Atmospheric Pressure CVD Systems p. 367
- Low-Pressure Chemical Vapor Deposition (LPCVD) p. 371
- Plasma-enhanced CVD (PECVD) p. 373

- Vapor Phase Epitaxy (VPE) p. 376
- Molecular Beam Epitaxy (MBE) p. 377
- Metalorganic CVD (MOCVD) p. 378
- Deposited Films p. 379
- Deposited Semiconductors p. 380
- Epitaxial Silicon p. 380
- Polysilicon and Amorphous Silicon Deposition p. 386
- SOS and SOI p. 388
- Insulators and Dielectrics p. 389
- Conductors p. 392
- Key Concepts and Terms p. 393
- Review Questions p. 393
- References p. 393
- Chapter 13. Metallization p. 395
- Introduction p. 396
- Conductors-Single Level Metal p. 396
- Conductors-Multilevel Metal Schemes p. 397
- Conductors p. 398
- Metal Film Uses p. 405
- Deposition Methods p. 407
- Vacuum Pumps p. 416
- Key Concepts and Terms p. 422
- Review Questions p. 422
- References p. 424
- Chapter 14. Process and Device Evaluation p. 427
- Introduction p. 428
- Wafer Electrical Measurements p. 429
- Physical Measurement Methods p. 434
- Layer Thickness Measurements p. 435
- Junction Depth p. 440
- Critical Dimensions (CD) and Line Width Measurements p. 443
- Contamination and Defect Detection p. 446
- General Surface Characterization p. 453
- Contamination Identification p. 454
- Device Electrical Measurements p. 457
- Key Concepts and Terms p. 466
- Review Questions p. 467
- References p. 467
- Chapter 15. The Business of Wafer Fabrication p. 469
- Fabrication and Factory Economics Overview p. 470
- Wafer-Fabrication Costs p. 471
- Equipment p. 477
- Cost of Ownership p. 479
- Automation p. 480
- Factory-Level Automation p. 483
- Equipment Standards p. 485

- Statistical Process Control (SPC) p. 487
- Inventory Control p. 492
- Line Organization p. 494
- Key Concepts and Terms p. 496
- Review Questions p. 496
- References p. 496
- Chapter 16. Semiconductor Devices and Integrated Circuit Formation p. 499
- Semiconductor-Device Formation p. 499
- Integrated-Circuit Formation p. 518
- Superconductors p. 529
- Microelectromechanical systems (MENS) p. 530
- Key Concepts and Terms p. 536
- Review Questions p. 537
- References p. 537
- Chapter 17. Integrated Circuit Types p. 539
- Introduction p. 539
- Circuit Basics p. 540
- Integrated-Circuit Types p. 542
- Wafer Scale Integration p. 552
- The Next Generation p. 553
- Key Concepts and Terms p. 554
- Review Questions p. 554
- References p. 555
- Chapter 18. Packaging p. 557
- Introduction p. 557
- Chip Characteristics p. 558
- Package Functions and Design p. 560
- Overview of Packaging Operations p. 561
- Packaging Processes p. 567
- Package Process Flows p. 584
- Package/Bare Die Strategies p. 585
- Package Design p. 586
- Package Type/technology Summary p. 591
- Key Concepts and Terms p. 592
- Review Questions p. 592
- References p. 592
- Glossary p. 595
- Index p. 615